

E&A 2023

Improve Time to Market and Optimize Processes with All-in-One Paste Jetting & Component Placing Solutions







Nano Dimension Portfolio Essemtec - Part of Nano Dimension

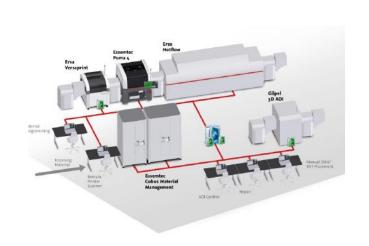


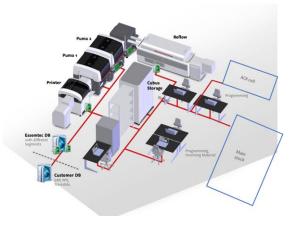
- DragonFly: Additively Manufactured Electronics
- Fabrica Group: Micro-AM solution for micron-resolution mechanical parts and manufacturing
- **Essemtec**: Adaptive, highly flexible SMT equipment, micro-dispensers, and intelligent production material logistics systems
- Global Inkjet Systems:
 Leading developer and supplier of software, drive electronics and ink system components

Driven by
DeepCube
Group: Deep
Learning
software
embedded in
printers and
systems for
realtime selflearning and
correction



Essemtec Solutions High-Mix Low-Mid Volume With Multiple Machine







- Feeder space
- All in one Archerfish
- Software friendly
- Factory concept
- Turtle Rabbit concept



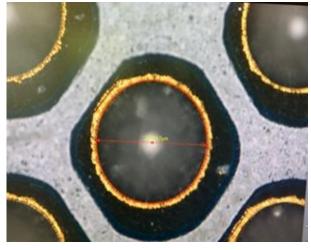






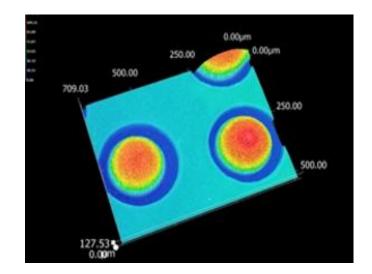
Solder Paste - Small dots

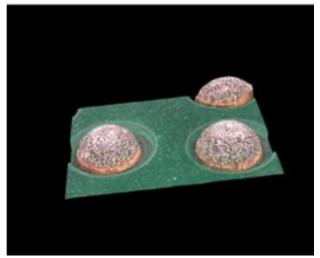






275um dots

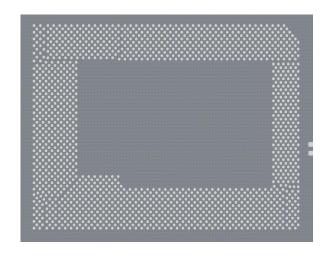


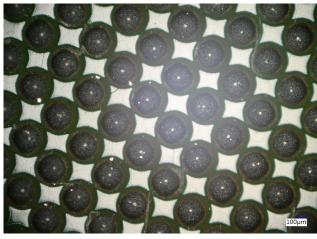


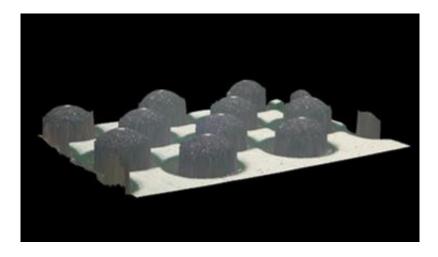




BGA Dispensing - Rework

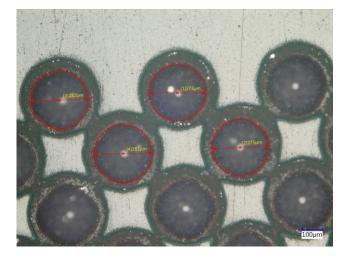




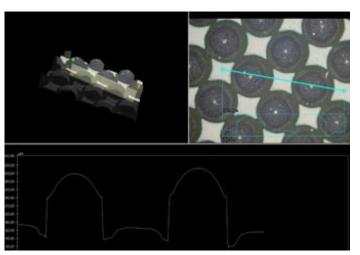


Special Nozzle





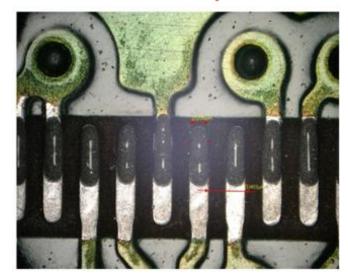
275um dots

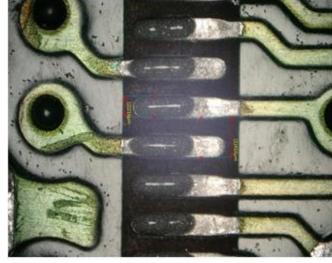




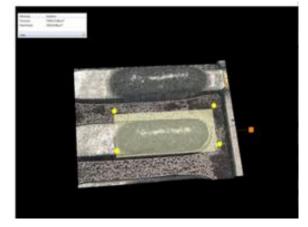
Fine Pitch

0.4mm fine pitch





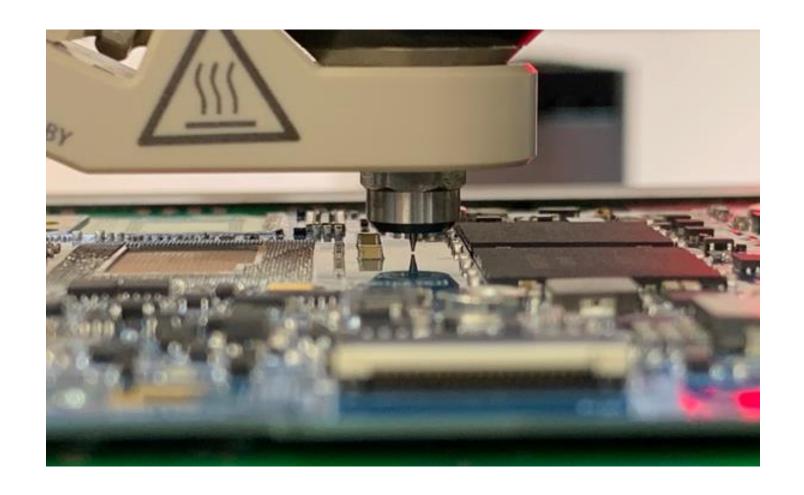








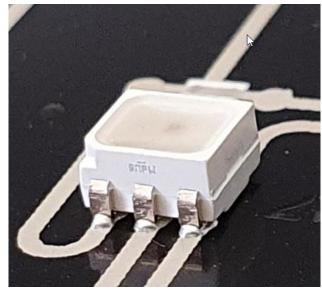
Repair Application

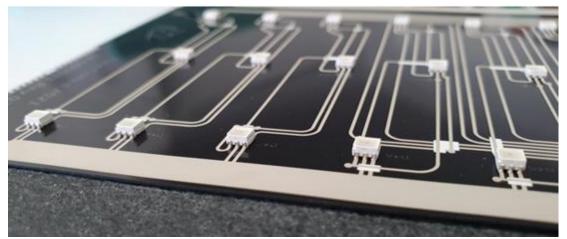




Flexible Surfaces Applications - LED









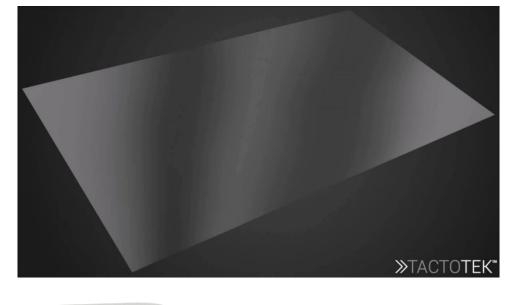
Printed Electronics Steps using IMSE technology





Mount components on **flat** film

3. Form 3D shape with components





Injection mold final single, seamless part



Printed Electronics Applications

Illuminated Boarding





Clean, Bright Disinfecting Surfaces

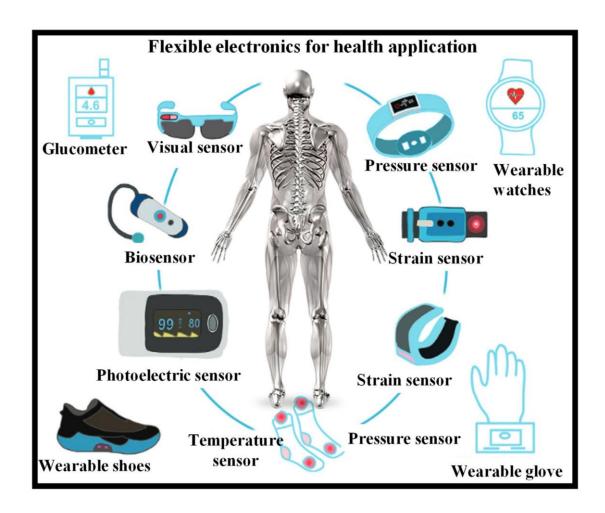
Room Seating







Printed Electronics In Healthcare









Customers references - Printed Electronics

Flexible keyboards









IMSE and Smart Surfaces







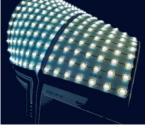




An AMBITIO Company













Combined Process

- Placing & dispensing in single pass-through
- Jet dispensing with up to 145'000 dots/h
- 5 different valves for all dispensing processes
- Solder Paste Jet Printing Integration
- All retrofittable







Valve Portfolio

TIME PRESSURE



MICRO SCREW

VOLUME



PIEZO JET

SHOCKWAVE JET



VTP-TP1000

Medium speed

Stable dispensing results

or simple glue & solder paste, fill applications, mid to high volumes

Speed^(*): 28.000 dots/h

IPC9850A: ~20.000 dots/h



VSR-MV

Low/medium speed

Constant and stable dispensing results

For all adhesives & solder paste, dam applications

Viscosity: medium

Speed^(*): 24.000 dots/h

IPC9850A: ~18.000 dots/h VVD-EP300

Medium speed

Constant and stable dispensing results

For sealing, gasketing, dam & fill applications, small to high volumes

Speed^(*): ~28.000 dots/h

IPC9850A: ~20.000 dots/h **VJV-3200A**

Highest speed

Constant and stable dispensing results

For wide range of applications, special for adhesives

Viscosity: low-high

Speed^(*): ~150.000 dots/h

> IPC9850A: ~60.000 dots/h

VDST-1560

Fast speed

Constant and stable dispensing results

> Special for solder paste

Viscosity: very high

Speed^(*): ~80.000 dots/h

> IPC9850A: ~40.000 dots/h

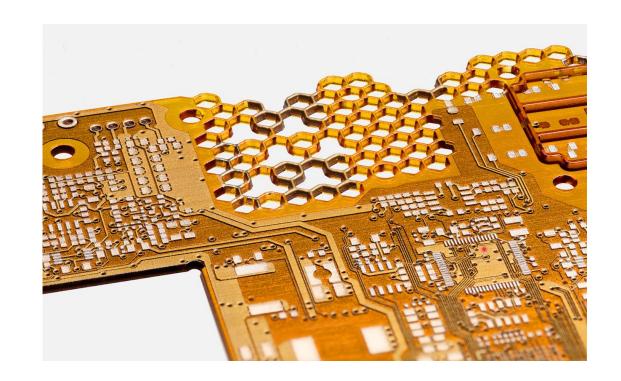


What Comes Next?

Nano Dimension - Additively Manufactured Electronics - AME has a very great future.

What is it about:

- The ability to print fully 3D functional circuits and high-performance devices, providing the industry with a growing alternative to conventional PCB manufacturing.
- This can be delivered in one production step and within hours from CAD to finished product







smd tec



Thank you



Meet us at Smd-Tec stand 7F071 and at the Demoplein

Kevin Domancich

Essemtec Head of Customer Application Engineering

Tom Van Tongelen Smd-Tec CEO





26 T/M 28 SEPTEMBER '23 JAARBEURS UTRECHT